

In the Claims:

This listing of claims replaces all prior versions, and listings, of claims in this application.

1. (Currently Amended) A camera module comprising:
an image sensor chip comprising a semiconductor chip having a photoelectronic transducer formed on a surface of the semiconductor chip and a filter portion disposed on the photoelectronic transducer so as to block light incident on the filter portion at a predetermined range of wavelength; and
a lens disposed above the image sensor chip,
wherein the filter portion is configured to provide mechanical support to the semiconductor chip regardless of the orientation of the semiconductor chip.
2. (Canceled)
3. (Original) The camera module of claim 1, wherein the filter portion comprises a glass plate and a metal film formed on a surface of the glass plate by vapor deposition.
4. (Original) The camera module of claim 1, wherein the filter portion comprises a plastic plate and a grating formed on a surface of the plastic plate so as to provide a filtering function
5. (Original) The camera module of claim 1, wherein the filter portion comprises a glass plate doped with copper particles or a plastic plate doped with the copper particles.
6. (Original) The camera module of claim 1, wherein the semiconductor chip comprises an electrode pad disposed on the surface of the semiconductor chip that does not have the photoelectronic transducer formed thereon.
7. (Original) The camera module of claim 6, wherein the image sensor chip comprises a terminal for external connection disposed on a back surface of the image sensor chip and connected to the electrode pad.